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P. Walker  
1-17-02

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Inventor(s): Tae Heon LEE et al.

U.S. Serial No.: 09/687,048  
U.S. Filing Date: October 13, 2000  
Art Unit: 2811

Priority Claim: KR 99-44650  
Priority Date: October 15, 1999

Title of Invention: LEADFRAME AND SEMICONDUCTOR PACKAGE WITH IMPROVED SOLDER JOINT STRENGTH

Attorney Reference: 45475-00026  
99-44650

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Assistant Commissioner for Patents  
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**PRELIMINARY AMENDMENT**  
**WITH REPLACEMENT SECTION UNDER RULE 1.121(b)**

Applicants respectfully request the Examiner to consider the following amendment and comments.